## **100V N-CHANNEL ENHANCEMENT MODE MOSFET**

### **SUMMARY**

 $V_{(BR)DSS}$ = 100V;  $R_{DS(ON)}$ = 0.6 $\Omega$   $I_D$ = 1.8A

### **DESCRIPTION**

This new generation of TRENCH MOSFETs from Zetex utilises a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



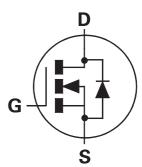
SOT223

#### **FEATURES**

- Low on-resistance
- · Fast switching speed
- · Low threshold
- Low gate drive
- SOT223 package

### **APPLICATIONS**

- DC DC Converters
- Power Management Functions
- Relay and Solenoid driving
- Motor control

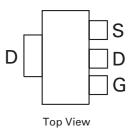


### **ORDERING INFORMATION**

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMN10A11GFTA	7″	12mm	1000 units
ZXMN10A11GFTC	13"	12mm	4000 units

#### **DEVICE MARKING**

 ZXMN 10A11





#### **ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DSS</sub>	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current $V_{GS}=10V$ ; $T_A=25^{\circ}C(b)$ $V_{GS}=10V$ ; $T_A=70^{\circ}C(b)$ $V_{GS}=10V$ ; $T_A=25^{\circ}C(a)$	ID	1.8 1.4 1.3	А
Pulsed Drain Current (c)	I <sub>DM</sub>	5.8	А
Continuous Source Current (Body Diode) (b)	IS	4.6	А
Pulsed Source Current (Body Diode)(c)	I <sub>SM</sub>	5.8	А
Power Dissipation at T <sub>A</sub> =25°C (a) Linear Derating Factor	PD	2 16	W mW/°C
Power Dissipation at T <sub>A</sub> =25°C (b) Linear Derating Factor	PD	3.9 31	W mW/°C
Operating and Storage Temperature Range	T <sub>j</sub> :T <sub>stg</sub>	-55 to +150	°C

## THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	62.5	°C/W
Junction to Ambient (b)	$R_{\theta JA}$	32	°C/W

### NOTES

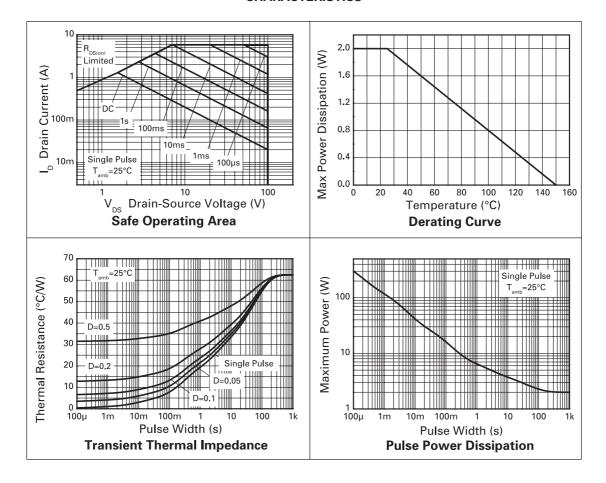
(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions



<sup>(</sup>b) For a device surface mounted on FR4 PCB measured at t≤10 secs.

(c) Repetitive rating 25mm x 25mm FRA PCB, D=0.05 pulse width = 10μs - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

#### **CHARACTERISTICS**





## **ELECTRICAL CHARACTERISTICS** (at TA = 25°C unless otherwise stated)

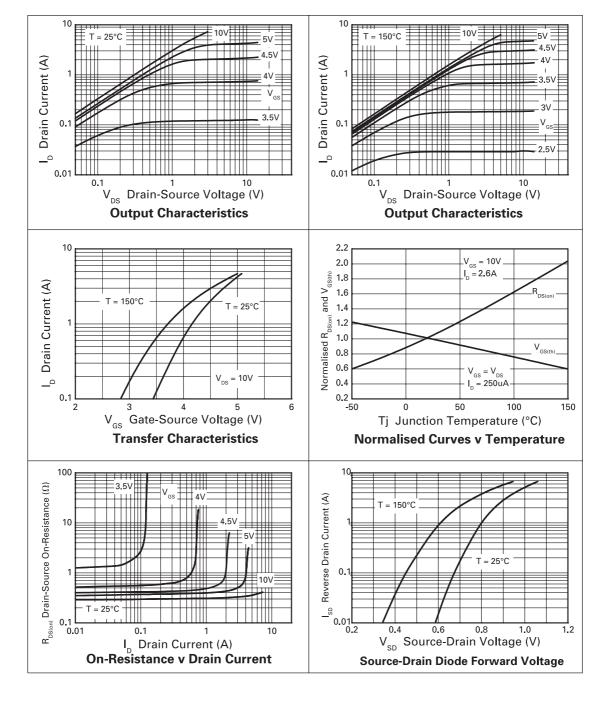
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.	
STATIC			•		,		
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	100			V	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			1	μΑ	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	
Gate-Body Leakage	IGSS			100	nA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	2.0		4.0	V	I <sub>D</sub> =250μA, V <sub>DS</sub> = V <sub>GS</sub>	
Static Drain-Source On-State Resistance (1)	R <sub>DS(on)</sub>			0.60 0.70	$\Omega$	V <sub>GS</sub> =10V, I <sub>D</sub> =2.6A V <sub>GS</sub> =6V, I <sub>D</sub> =1.3A	
Forward Transconductance (3)	9fs		3.95		S	V <sub>DS</sub> =15V,I <sub>D</sub> =2.6A	
DYNAMIC (3)			•				
Input Capacitance	C <sub>iss</sub>		274		pF		
Output Capacitance	Coss		21		pF	V <sub>DS</sub> =50 V, V <sub>GS</sub> =0V,	
Reverse Transfer Capacitance	C <sub>rss</sub>		11		pF		
SWITCHING(2) (3)							
Turn-On Delay Time	t <sub>d(on)</sub>		2.7		ns		
Rise Time	t <sub>r</sub>		1.7		ns	V <sub>DD</sub> =50V, I <sub>D</sub> =1A R <sub>G</sub> =6.0Ω, V <sub>GS</sub> =10V	
Turn-Off Delay Time	t <sub>d(off)</sub>		7.4		ns		
Fall Time	t <sub>f</sub>		3.5		ns		
Gate Charge	$Q_g$		3		nC	V <sub>DS</sub> =50V, V <sub>GS</sub> =5V, I <sub>D</sub> =2.5A	
Total Gate Charge	Qg		5.4		nC	V <sub>DS</sub> =50V,V <sub>GS</sub> =10V, I <sub>D</sub> =2.5A	
Gate-Source Charge	Qgs		1.4		nC		
Gate-Drain Charge	Q <sub>gd</sub>		1.5		nC	-10-2.00	
SOURCE-DRAIN DIODE		•	•		•		
Diode Forward Voltage (1)	V <sub>SD</sub>		0.85	0.95	V	T <sub>J</sub> =25°C, I <sub>S</sub> =1.85A, V <sub>GS</sub> =0V	
Reverse Recovery Time (3)	t <sub>rr</sub>		26		ns	T <sub>J</sub> =25°C, I <sub>F</sub> =1.0A,	
Reverse Recovery Charge (3)	Q <sub>rr</sub>		30		nC	di/dt= 100A/μs	

#### NOTES

- (1) Measured under pulsed conditions. Width  $\!\leq\!300\mu s.$  Duty cycle  $\!\leq\!2\%$  .
- (2) Switching characteristics are independent of operating junction temperature.
- (3) For design aid only, not subject to production testing.



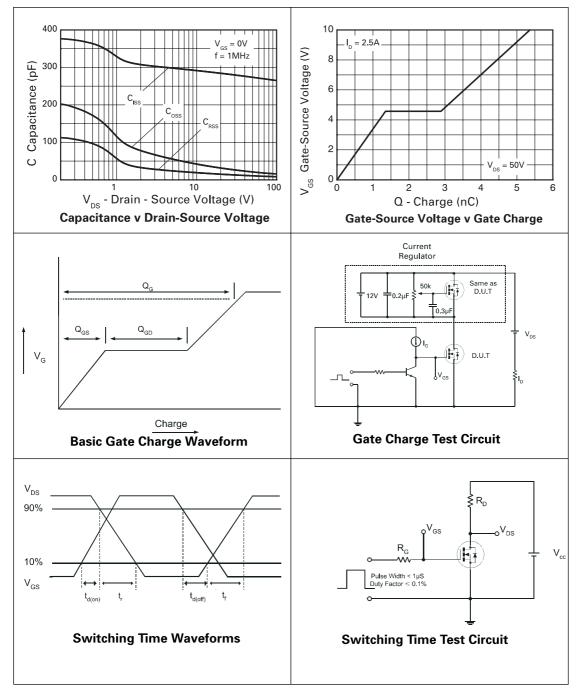
#### **TYPICAL CHARACTERISTICS**



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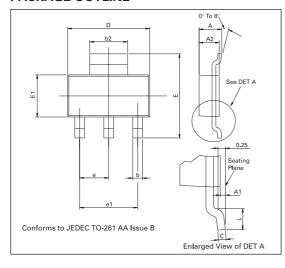
#### **TYPICAL CHARACTERISTICS**





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#### **PACKAGE OUTLINE**



#### **PACKAGE DIMENSIONS**

	MILLIMETRES		
DIM	IVIILLIIVIL ITILS		
	MIN	MAX	
Α	_	1.80	
A1	0.02	0.10	
A2	1.55	1.65	
b	0.66	0.84	
b2	2.90	3.10	
С	0.23	0.33	
D	6.30	6.70	
е	2.30 BASIC		
e1	4.60 BASIC		
Е	6.70	7.30	
E1	3.30	3.70	
L	0.90	_	

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